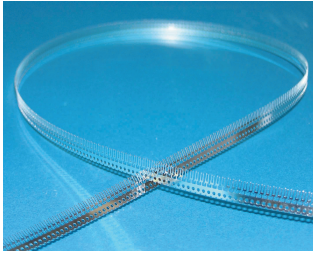


Surface Treatment Chemical for Electronic Parts

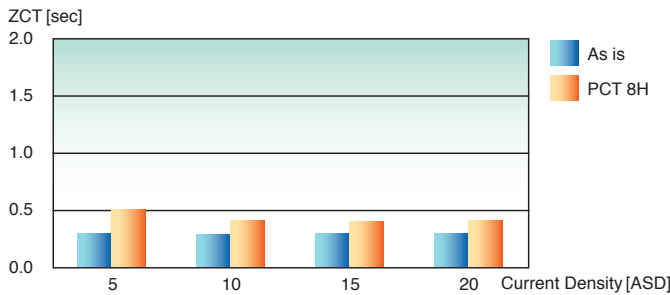


Low carbon type bright Sn plating process (METASU SNV-300)



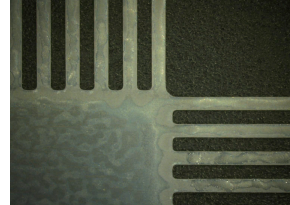
- 1) Does not cause change in surface film after reflow (No drawing).
- 2) Decrease change in color after reflow and no degradation for solder-wettability.
- 3) It has good resistance against scratching.

The Solder-Wettability of METASU SNV-300

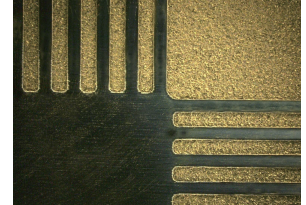


■ No big degradation for solder-wettability after PCT.

Appearance after reflow (As is)

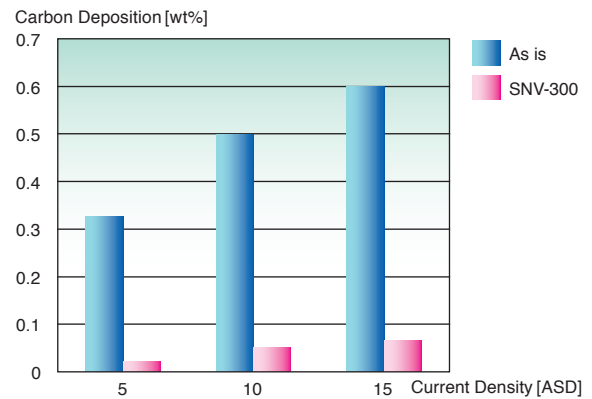


Appearance after reflow (METASU SNV-300)



■ It gas great appearance after reflow.

Comparison of Carbon Deposition



■ When compared, METASU SNV-300 has much lower carbon deposition.

Sealer for Au plating (METASU HS-15)

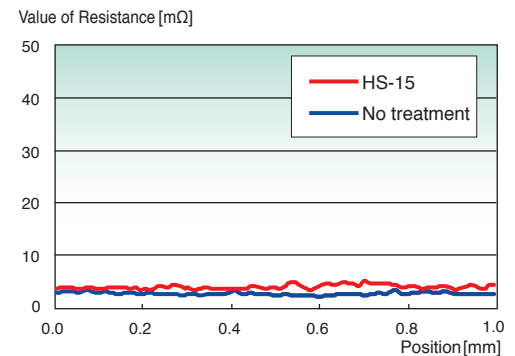
- 1) Excellent anti-corrosion performance against corrosion environments such as HNO₃.
- 2) No degradation for contact resistance and solder-wettability after treatment of METASU HS-15.
- 3) No stains regardless of rinsing or no rinsing because of no-emulsion type.

Corrosion Resistance (Evaluation after 60sec. under 260°C)

| | as-plated | HNO ₃ (1hr) | SO ₂ Gas(96hr) | SST(48hr) |
|------------|-----------|------------------------|---------------------------|-----------|
| As is | | | | |
| With HS-15 | | | | |

■ It is proven that there is a significant improvement on resistance performance.

Contact Resistance (5gf · 1mm move)



■ No change in contact resistance after METASU HS-15.